

## Dry Heat Test Report

Issue by

**Certification Center**

<b>Product Model</b>	<b>5.7" Rugged Handheld Device : R05I98H-RTD1</b>
<b>Product Description</b>	<b>Rugged Handheld Device</b>
<b>Test Reason</b>	<input checked="" type="checkbox"/> New product <input checked="" type="checkbox"/> Rugged Handheld Device  <input type="checkbox"/> Renew product <input type="checkbox"/> PCB : <input type="checkbox"/> BIOS:  <input type="checkbox"/> Revision change <input type="checkbox"/> PCB : <input type="checkbox"/> BIOS: <input type="checkbox"/> Component:

2011/10/12  
Issue date

Lindon Lin  
Approved

Freeman Lee  
Test Engineer

## 1. Document Introduction and Revision History

This document describes how we conduct the environment conditions and test procedure. It includes the test equipment we use, the test condition, and the test procedure we take. We also define our test criteria and the way to conclude the test result.

(According to client's test specification, please see following sheets in detail.)

**Table of Testing Summary Results**

NO	Test Item	Condition Description	Sect. / Page	Reference to
1	High Temperature Test	Storage Basic Hot Temperature: +30 to 63°C ± 2°C For a period of 168 Hours	4 / 5	MIL-STD-810F Method 501.4 Procedure I

## 2. Product Configuration

1. M/B : Winmate I98H5-110
2. CPU : Intel® Atom™ Processor Z510 @ 1.10 GHz
3. Chipset : Intel US15W
4. RAM : Transcend TS128MSQ64V6U SODIMM DDR2-667 1GB
5. SSD : PQI D10080G57RW01A70 MiniPCIe PATA SSD 8G MLC
6. Panel : DataImage 050722DSSWDG01 640x480
7. Battery : FSP RTB-057HH Li-Ion Battery 2S1P 7.4V 2600mAh x 2
8. Bluetooth : Q-COM Bluetooth QBT400-USB01p
9. 3G : HUAWEI EM770W HSPA Module
10. GPS : u-blox LEA-6S GPS Module
11. Wifi : Wi2Wi W2SW0001 WLAN SIP 802.11b/g
12. Adapter : EDAC EA1050C-120 / AC IN 100-240V~1.8A,50-60Hz / DC OUT 12V,4.16A
13. Hot Tab / EC : 205\_H5 / 212

### 3. High Temperature Test- Storage

#### A. Test Equipment:

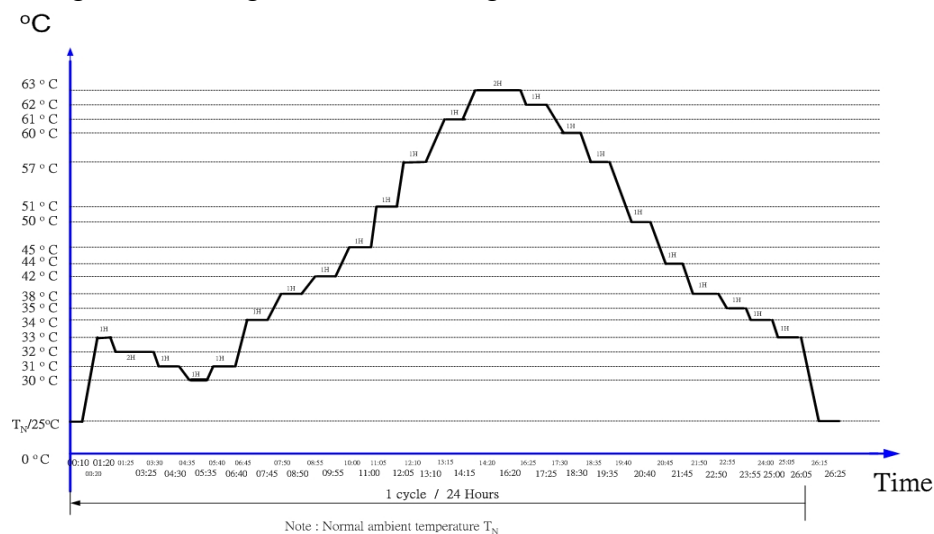
- Test Site: Winmate LAB
- Programmable Temperature & Humidity Chamber
- KSON / THS-E4C-100 / S/N: 3087

#### B. LAB Environmental Conditions:

- Ambient Temperature :25 +/- 3°C
- Relative Humidity: 55 +/- 20% RH

#### C. Test Method / Specification :

- Reference to MIL-STD-810F Method 501.4 Testing Procedures
- Selecting Produces: Procedure I / Storage / Basic Hot
- Reference to Table 501.4-III. Summary of high temperature diurnal cycle range.
- Temperature:+30 to 63°C ± 2°C
- For a period of 168 Hours (7 Cycles)
- Quantity: Total 1 Set
- Testing Period: Aug. 05, 2011 to Aug. 13, 2011



**Figure 1: High Temperature, temperature cycle**

#### **D. Check Condition and Requirements:**

After the preconditioning time, the temperature cycle is started at normal ambient temperature  $T_N$  and run as shown in Fig.1. The equipment in its high temperature mode, shall exposed to daily high temperature cycles between 24 Hours at 30 to 63°C .The equipment shall withstand the required environmental conditions and shall meet, without any functional damage, all performance requirements after being exposed to 7 cycles of high temperatures, as illustrated in Figure 1.

Performance check: Running Windows XP with PassMark BurnIn Test Professional V6.0 (Build 1030)

#### **E. Test Result:**

Examine the appearance of specimen(s) by visual check and perform functional check after this test. Connect the specimen with rated power then examine whether the display function of specimen could be work normally or not.

- Functional Check & Mechanical Structure: Normal
- Appearance check (Visual check): No visible damage
- The requirements of the performance test and check shall be met.

#### **F. Test Judgment:**

— Test Result as below:

Check Item Style Item No.	Appearance check (Visual check)		Functional & Performance check
	Initial	Final	
<b>5.7" Rugged Handheld Device: R05I98H-RTD1</b>	No visible damage	No visible damage	Normal